



THE DATASHEET OF SF2136E



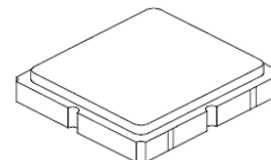
- Steep Roll-off Filter for 433.92 MHz Unlicensed Band
- No Matching Required for Operation in 50Ω Environment
- Complies with Directive 2002/95/EC (RoHS)
- Moisture Sensitivity Level: 1

Absolute Maximum Ratings

Rating	Value	Units
Input Power Level	10	dBm
DC Voltage on any Non-ground Terminal	3	V
Operating Temperature Range	-40 to +85	°C
Storage Temperature Range in Tape and Reel	-40 to +85	°C
Maximum Soldering Profile, 5 Cycles/10 seconds Maximum	265	°C

SF2136E

**433.92 MHz
SAW Filter**



SM3030-6

Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	f_C			433.92		MHz
3 dB Bandwidth				5		MHz
Insertion Loss, 433.05 to 434.79 MHz	IL			2.0	3.3	dB
Amplitude Ripple, p-p, 433.05 to 434.79 MHz				0.3	1.5	
Attenuation Referenced to 0 dB:						
389.0 to 392.0 MHz			42	54		
411.0 to 414.0 MHz			40	50		
454.0 to 457.0 MHz			40	51		
475.0 to 478.5 MHz			42	52		
863.0 to 870.0 MHz			41	35		
Source Impedance	Z_S			50		Ω
Load Impedance	Z_L			50		Ω

Case Style	SM3030-6 3.0 x 3.0 mm Nominal Footprint
Lid Symbolization, Y=year, WW=week, S=shift, Dot=pin 1 indicator	682, <u>YWWS</u>

Electrical Connections

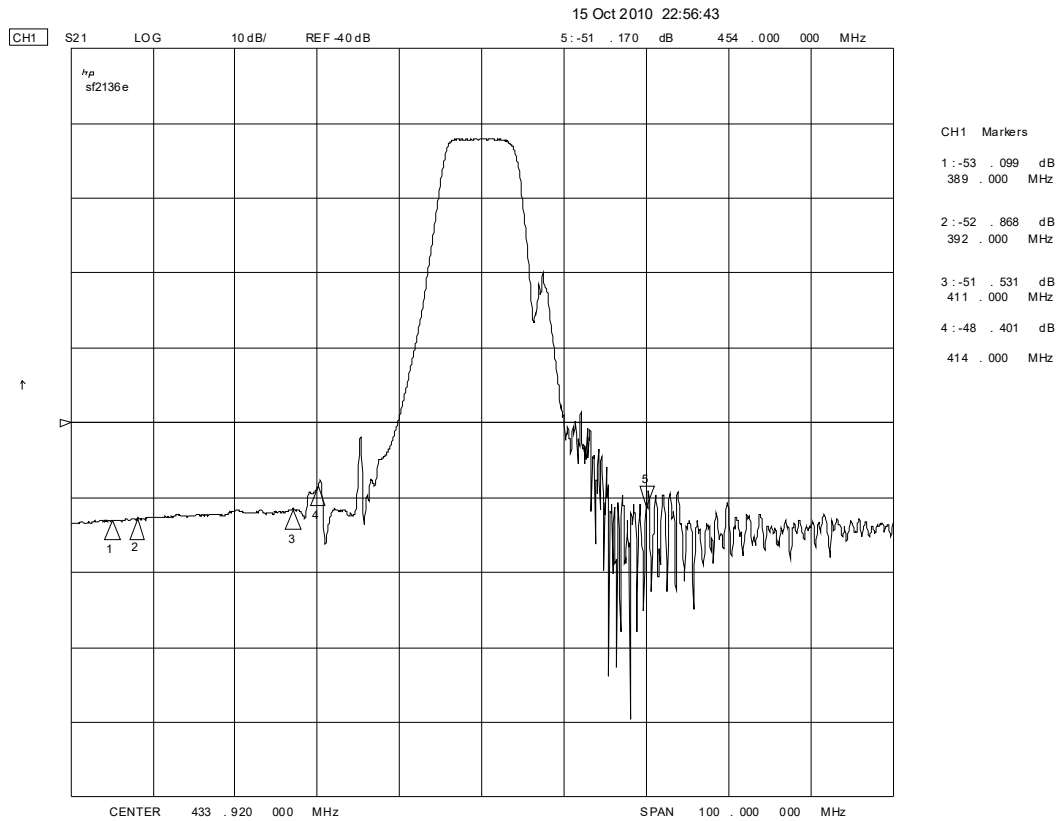
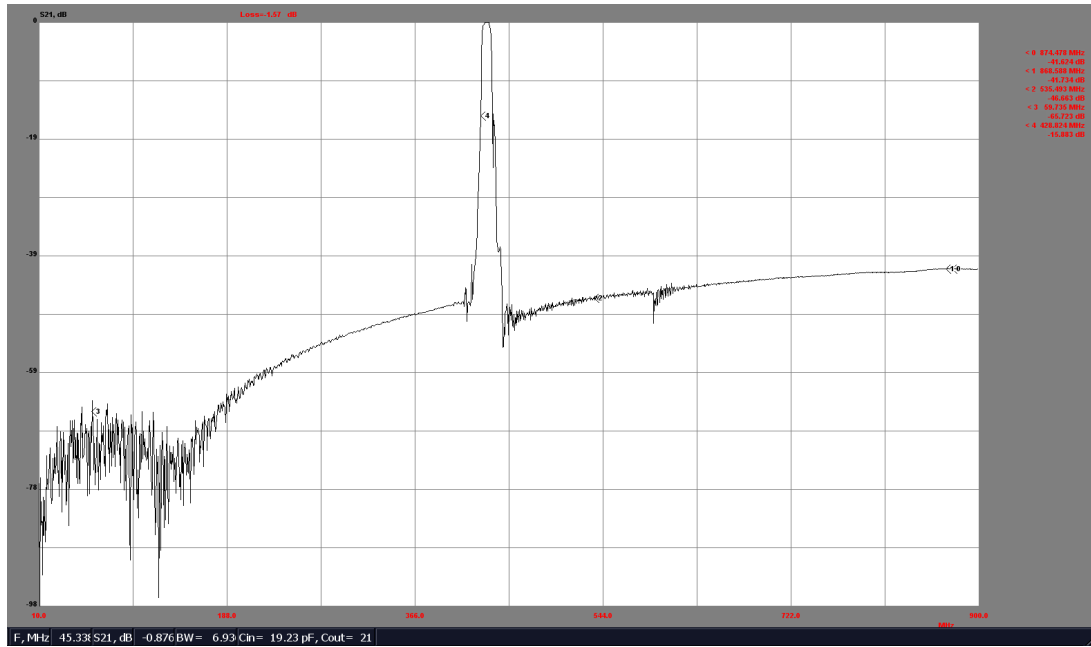
Connection	Terminals
Input	2
Output	5
Case Ground	All others

 **CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.**

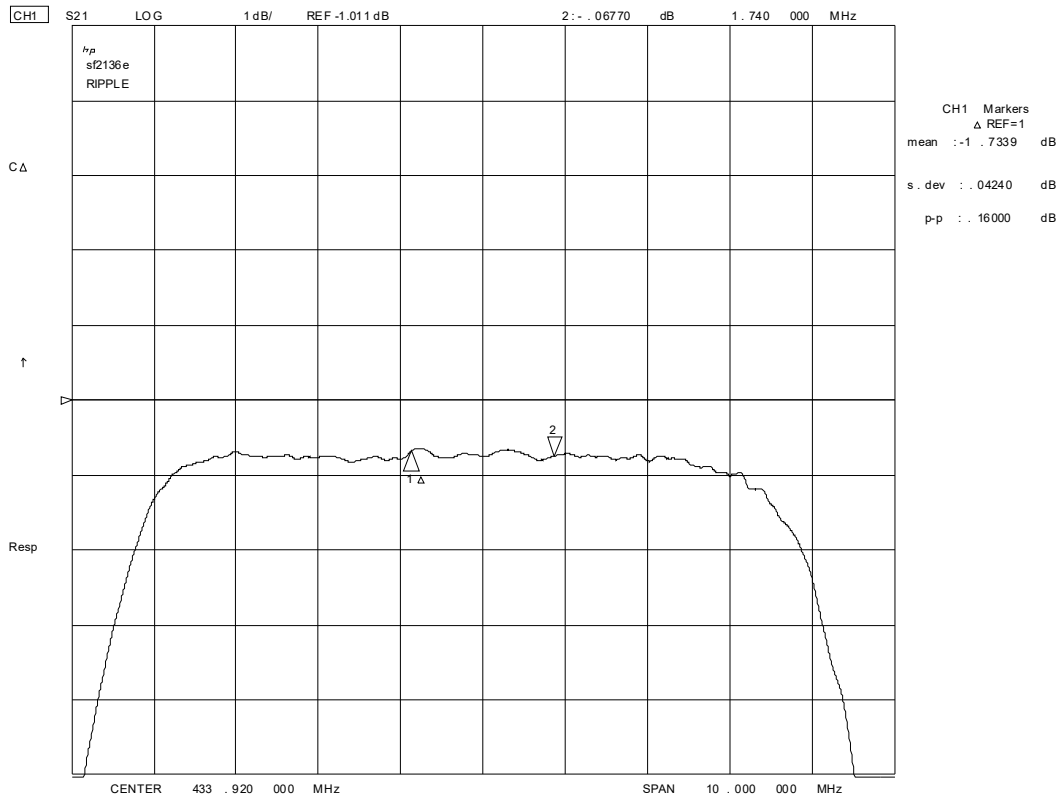
NOTES:

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.

SF2136E Frequency Response Plots

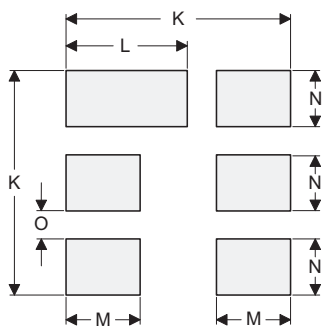
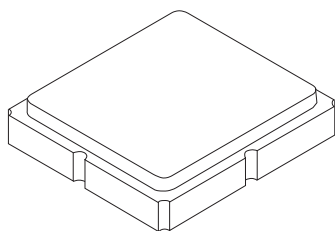


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SM3030-6 Case

6-Terminal Ceramic Surface-Mount Case 3.0 X 3.0 mm Nominal Footprint



PCB Footprint Top View

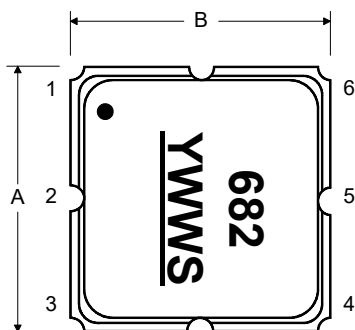
Case and PCB Footprint Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.87	3.00	3.13	0.113	0.118	0.123
B	2.87	3.00	3.13	0.113	0.118	0.123
C	1.12	1.25	1.30	0.044	0.049	0.051
D	0.77	0.90	1.03	0.030	0.035	0.040
E	2.67	2.80	2.93	0.105	0.110	0.115
F	1.47	1.60	1.73	0.058	0.063	0.068
G	0.72	0.85	0.98	0.028	0.033	0.038
H	1.37	1.50	1.63	0.054	0.059	0.064
I	0.47	0.60	0.73	0.019	0.024	0.029
J	1.17	1.30	1.43	0.046	0.051	0.056
K		3.20			0.126	
L		1.70			0.067	
M		1.05			0.041	
N		0.81			0.032	
O		0.38			0.015	

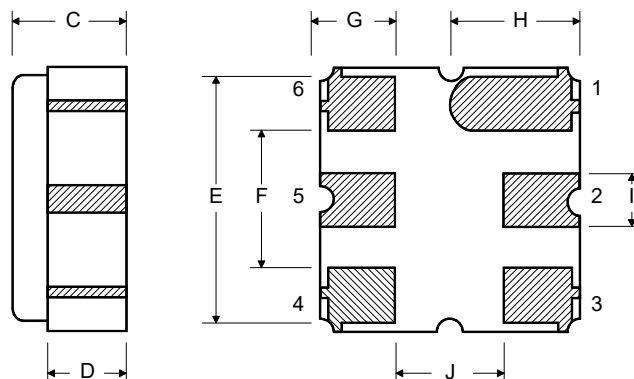
Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 μm Gold over 1.27 to 8.89 μm Nickel
Lid Plating	2.0 to 3.0 μm Nickel
Body	Al_2O_3 Ceramic

Top View

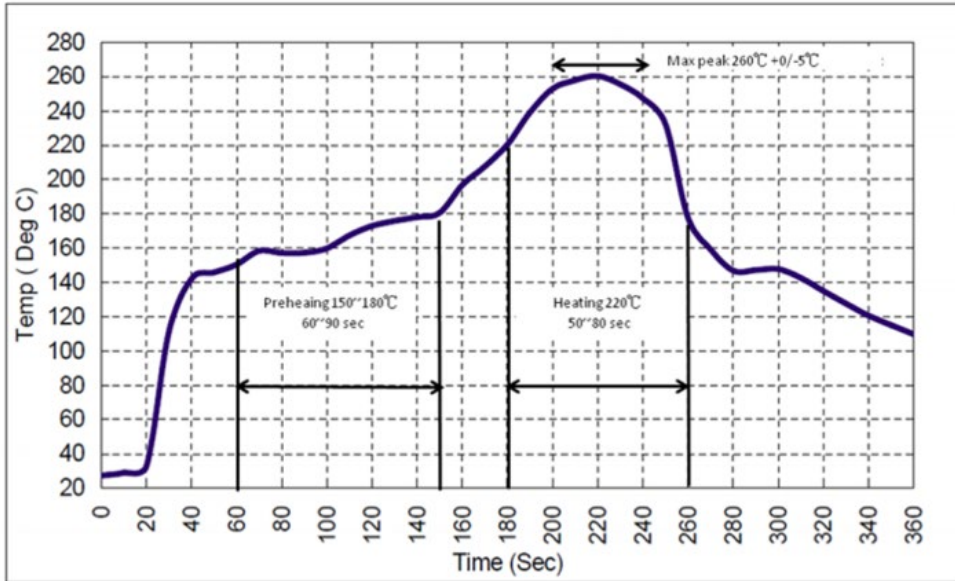


Bottom View



Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 seconds).
4. Time: 5 times maximum.



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